

CLAIMS

- [1] A cover film comprising at least a substrate layer (A), an intermediate layer (B), a peel layer (C) and a heat seal layer (D) capable of being heat-sealed to a carrier tape;

wherein the substrate layer (A) is a biaxially stretched polyester,
the intermediate layer (B) is a linear low-density polyethylene,
the peel layer (C) is a hydrogenated styrene-isoprene-styrene triblock
copolymer having a styrene content of 15 to 35 mass% or a hydrogenated
styrene-butadiene-styrene triblock copolymer having a styrene content of 15 to 35
mass%,

wherein the heat seal layer (D) comprises, as a main component, a
styrenic-acrylic copolymer having a mass-average molecular weight of 5000 to 20000,
and the styrenic-acrylic copolymer of the heat seal layer (D) is a resin having a glass
transition temperature of 70 to 100°C.

- [2] The cover film according to claim 1, wherein a thickness of the substrate
layer (A) is 12 to 25 μm , a thickness of the intermediate layer (B) is 10 to 40 μm , a
thickness of the peel layer (C) is 0.1 to 1.5 μm , and a thickness of the heat seal layer
(D) is 0.1 to 5 μm ~~The cover film according to claim 1, wherein the styrenic acrylic~~
~~copolymer of the heat seal layer (D) is a resin having a glass transition temperature of~~
~~70 to 100 °C.~~

- [3] ~~The cover film according to claim 1 or 2, wherein the peel layer (C)~~
~~comprises, as a main component, a hydrogenated aromatic vinyl-conjugated diene~~
~~copolymer having an aromatic vinyl content of 15 to 35 mass%.~~

- [43] The cover film according to ~~any one of claims 1 to 3~~ 2-3, wherein the peel
layer (C) and/or the heat seal layer (D) comprises a conductive material.

- [54] The cover film according to claim 43, wherein the conductive material is
conductive microparticles, comprising acicular or spherical microparticles, or a

combination thereof.

[65] The cover film recited in either claim 43 or 54, wherein the conductive material is a carbon nano-material.

[76] An electronic component package wherein the cover film according to any one of claims 1 to 65 is used as a lid material of a carrier tape having a thermoplastic resin as the main component.